

# 250V N-Channel Enhancement Mode Power MOSFET

# **Description**

WML15N25T2 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

#### **Features**

- $V_{DS}$ = 250V,  $I_{D}$  = 15A  $R_{DS(on)}$  < 238m $\Omega$  @  $V_{GS}$  = 10V  $R_{DS(on)}$  < 270m $\Omega$  @  $V_{GS}$  = 4.5V
- High Speed Power Smooth Switching, Logic Level
- Lead Free
- 100% EAS Guaranteed

## **Applications**

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- UPS
- Motor Control
- Power Tools

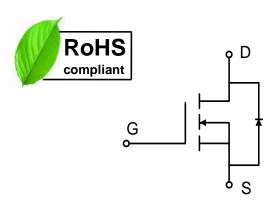
## **Absolute Maximum Ratings**

Parameter  Drain-Source voltage		Symbol	Value	Unit V	
		V <sub>DS</sub>	250		
Gate-Source voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current <sup>1</sup>	Tc=25°C	1_	15	Α	
	Tc=100°C	- I <sub>D</sub>	6.5		
Pulsed Drain Current <sup>2</sup>		Ідм	44	А	
Single Pulse Avalanche Energy <sup>3</sup>		EAS	4	mJ	
Avalanche Current		I <sub>AS</sub>	4.5	А	
Total Power Dissipation <sup>4</sup>	T <sub>C</sub> =25°C	P <sub>D</sub>	22.7	W	
Operating Junction and Storage Temperature Range		T <sub>1</sub> , Tera	-55 to 150	°C	

## **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	R <sub>0JA</sub>	63	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	Rejc	5.5	°C/W







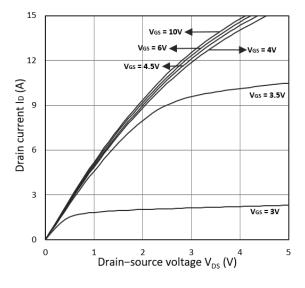
## Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics		1		l				
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	250	-	-	V	
Gate-body Leakage current		Igss	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain Current	T <sub>J</sub> =25°C	- I <sub>DSS</sub>	V <sub>DS</sub> = 250V, V <sub>GS</sub> = 0V	-	-	1 100	μA	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	1	2	3	V	
	2	_	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5A	-	185	238	†	
Drain-Source on-Resistance <sup>2</sup>		R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3A	-	195	270	mΩ	
Forward Transconductance <sup>2</sup>		<b>g</b> fs	V <sub>DS</sub> = 5V, I <sub>D</sub> = 20A	-	10	-	S	
Dynamic Characteristic	s			•	•			
Input Capacitance		Ciss	Ciss		525	-	pF	
Output Capacitance  Reverse Transfer Capacitance		Coss	V <sub>DS</sub> = 100V, V <sub>GS</sub> =0V, f =1MHz	-	35	-		
		C <sub>rss</sub>		-	6.2	-		
Switching Characteristi	cs							
Gate Resistance		R <sub>G</sub>	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	-	4.6	-	Ω	
Total Gate Charge		Qg	$V_{GS} = 4.5V, V_{DS} = 125V,$ $I_{D} = 3A$	-	5.8	-	- nC	
Total Gate Charge		Qg	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 150V,	-	11.2	-		
Gate-Source Charge		$\mathbf{Q}_{gs}$		-	3.2	-		
Gate-Drain Charge		$Q_{gd}$		-	7.2	-		
Turn-on Delay Time		t <sub>d(on)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =125V,	-	9.5	-	. nS	
Rise Time		tr		-	5.8	-		
Turn-off Delay Time		t <sub>d(off)</sub>	$R_G = 10\Omega$ , $I_D = 3A$	-	14.5	-		
Fall Time		t <sub>f</sub>	_	-	4.8	-		
Drain-Source Body Dio	de Characte	ristics						
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1	V	
Continuous Source Current <sup>1,5</sup>		Is	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	15	Α	
Body Diode Reverse Recov	ery Time	t <sub>rr</sub>	L 0A W/W 100A/	-	39	-	nS	
Body Diode Reverse Recovery Charge		Qrr	- I <sub>F</sub> = 3A, dI/dt=100A/μs	-	80	-	nC	

#### Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%.
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =50V,  $V_{GS}$ =10V, L=0.4mH,  $I_{AS}$ =4.5A.
- 4. The power dissipation is limited by 150°C junction temperature.
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation.





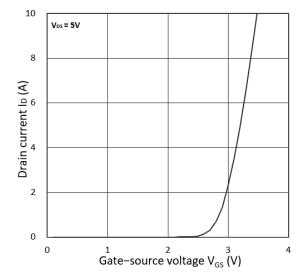
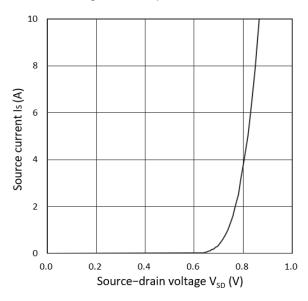


Figure 1. Output Characteristics

Figure 2. Transfer Characteristics



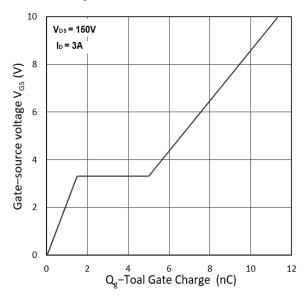
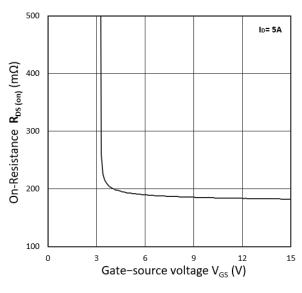


Figure 3. Forward Characteristics of Reverse

Figure 4. Gate Charge Characteristics



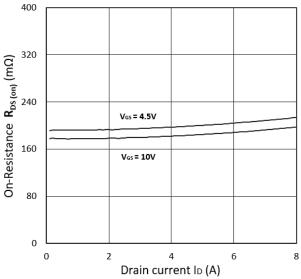
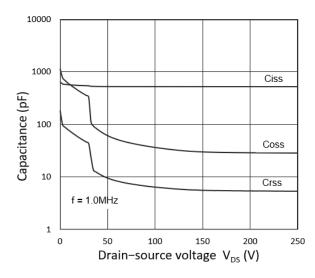


Figure 5. R<sub>DS(on)</sub> vs. V<sub>GS</sub>

Figure 6. R<sub>DS(on)</sub> vs. I<sub>D</sub>





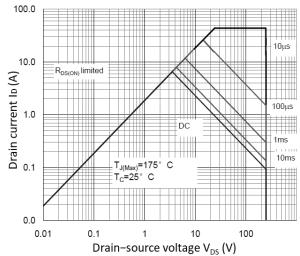


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

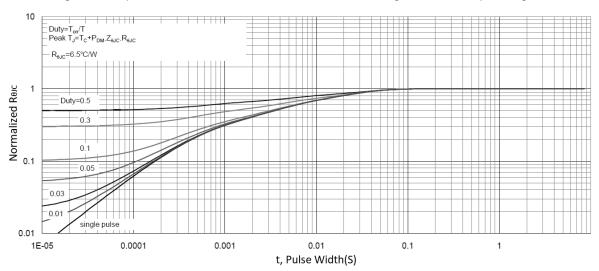
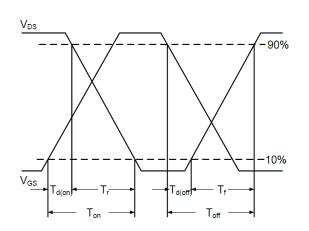


Figure 9. Normalized Maximum Transient Thermal Impedance



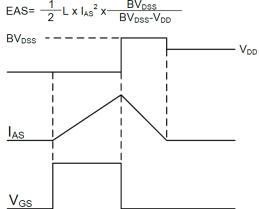


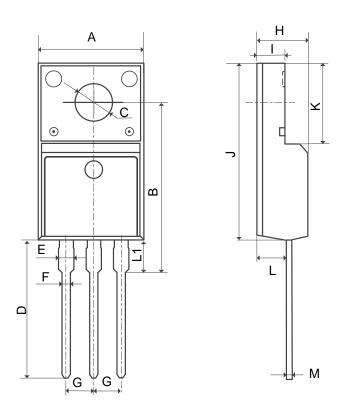
Figure 10. Switching Time Waveform

Figure 11. Unclamped Inductive Switching

Waveform



#### **Mechanical Dimensions for TO-220F**



## **COMMON DIMENSIONS**

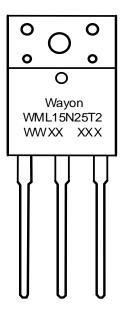
CVMDOL	MM			
SYMBOL	MIN	MAX		
А	9.96	10.36		
В	15.10	16.10		
С	3.03	3.38		
D	12.64	13.38		
Е	1.18	1.58		
F	0.65	0.95		
G	2.54REF			
Н	4.50	4.90		
I	2.34	2.74		
J	15.57	16.17		
K	6.70REF			
L	2.56	2.96		
M	0.40	0.60		
L1	2.85	3.50		



## **Ordering Information**

Part	Package	Marking	Packing method
WML15N25T2	TO-220F	WML15N25T2	Tube

## **Marking Information**



WML15N25T2 = Device code WWXX XXX= Date code

## **Contact Information**

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For additional information, please contact your local Sales Representative.

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